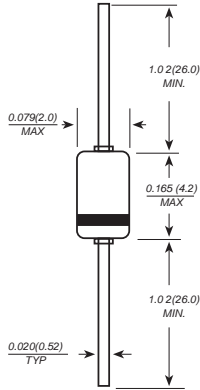


DB3

BIDIRECTIONAL TRIGGER DIODE

Reverse Voltage - 32 Volts Power: 150mW

DO-35(GLASS)



Dimensions in inches and (millimeters)

FEATURES

- ◆ Small glass structure ensures high reliability
- ◆ VBO:26-36V version
- ◆ Low breakover current
- ◆ High temperature soldering guaranteed
250°C/10 seconds, 0.375"(9.5mm) lead length,
5 lbs. (2.3kg) tension

MECHANICAL DATA

Case: JEDEC DO-35 glass body

Terminals: Plated axial leads, solderable per MIL-STD-750,
Method 2026

Mounting Position: Any

Weight: 0.005 ounce, 0.14gram

MAXIMUM RATINGS AND CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

	TEST CONDITION	SYMBOLS	VALUE			UNITS
			Min.	Typ.	Max.	
Breakover voltage *	C=22nF **	V _{BO}	28	32	36	VOLTS
Breakover voltage symmetry	C=22nF **	+V _{BO} -I-V _{BO}	-3		3	VOLTS
Dynamic breakover voltage *	(NOTE 1)	I D V ± I	5			VOLTS
Output voltage *	DIAGRAM2	V _o	5			VOLTS
Breakover current *	C=22nF **	I _{BO}			100	uA
Rise time *	DIAGRAM3	t _r		1.5		uS
Leakage current *	V _R =0.5V _{BO}	I _B			10	uA
Power dissipation on printed circuit	T _A =65°C	P _d			150	uW
Repetitive peak on-state current	t _p =20ms f=100Hz	I _{TRM}			2	A
Thermal Resistances from Junction to ambient		R _{QJA}			400	°C/W
Thermal Resistances from Junction to lead		R _{QJL}			150	
Operating junction and storage temperature range		T _J , T _{STG}	-40		125	°C

* :Electrical characteristic appoicaboe in forward and reverse directions.

** :Connected in parallel with the devices.

Note 1: I_F from to 10mA

RATINGS AND CHARACTERISTIC CURVES DB3

DIAGRAM 1: CURRENT-VOLTAGE CHARACTERISTICS

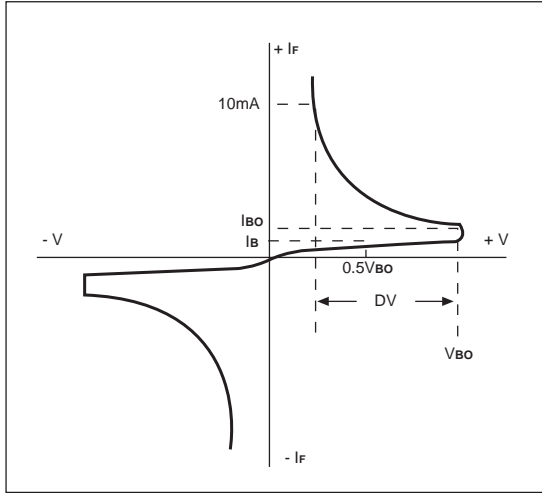


FIG. 1-POWER DISSIPATION VERSUS AMBIENT TEMPERATURE(MAXIMUM VALUES)

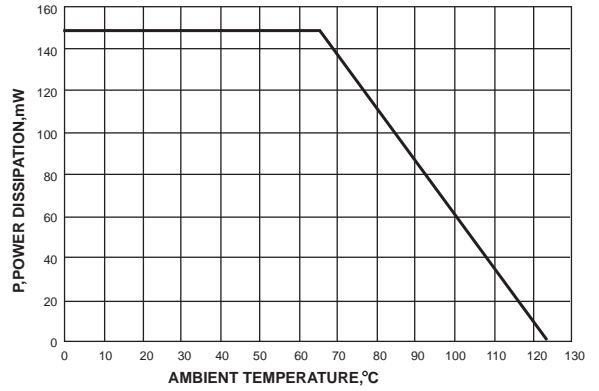


DIAGRAM 2: TEST CIRCUIT OUTPUT VOLTAGE

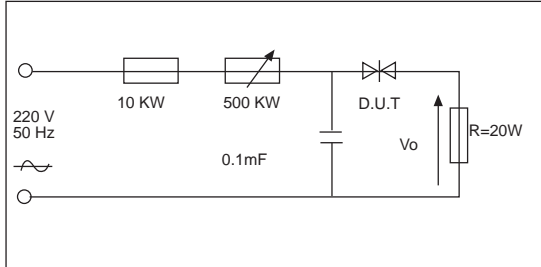


FIG. 2-PEAK PULSE CURRENT VERSUS PULSE DURATION (MAXIMUM VALUES)

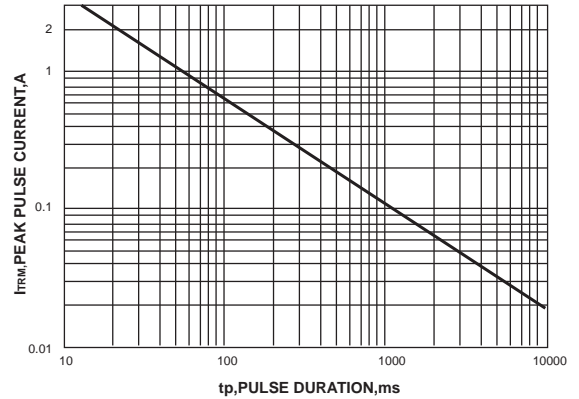


DIAGRAM 3: TEST CIRCUIT SEE DIAGRAM 2. ADJUST R FOR $I_p=0.5A$

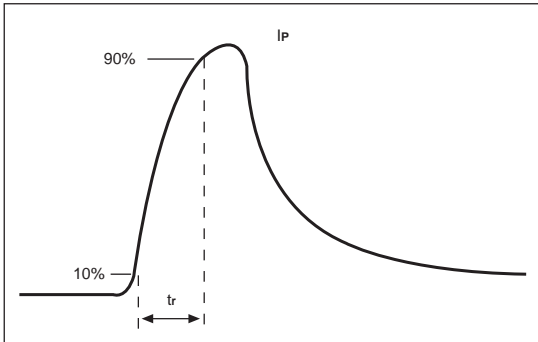


FIG. 3-RELATIVE VARIATION OF V_{Bo} VERSUS JUNCTION TEMPERATURE(TYPICAL VALUES)

